

IN THE CLAIMS:

Please amend the claims as follows:

1. (Currently Amended) A method for performing at least one operation of a testing operation and a burn-in operation on an uncut wafer having two opposing surfaces using a first plate which includes a biasing mechanism, and a second rigid plate selectively engageable with the first plate, the second rigid plate having a plurality of contact elements extending therefrom and having a cavity for receiving the uncut wafer therein, the method comprising:

providing a wafer having a plurality of semiconductor die thereon, each semiconductor die

having a plurality of bond pads;

placing the wafer, in a desired orientation, between the first plate and the second rigid plate with the plurality of contact elements on the second rigid plate engaging corresponding locations of the plurality of bond pads of the semiconductor die on the wafer, the second rigid plate receiving the wafer therein;

and

biasing the plurality of contact elements of the second rigid plate against a surface of the wafer by applying an elastic force to an opposing surface to the surface of the wafer with the first plate, the force caused by the biasing mechanism, and the force applied to substantially the entirety of the opposing surface.

2. (Original) The method as claimed in claim 1, wherein the wafer comprises a semiconductor wafer.

3. (Original) The method as claimed in claim 1, wherein the wafer includes an array of semiconductor dice located thereon.

4. (Original) The method as claimed in claim 1, further comprising:
aligning the first plate and the second rigid plate.

5.-24. (Cancelled)